



产品规格书/Specification

产品/product:	介质浆料/ Dielectric paste
料号/part number:	07MTHS400

适用范围/Application:

该款浆料适合于厚膜电路填孔,粘合、可用于陶瓷、玻璃、金属等基材。

The paste is suitable for through hole into thick film circuit、ceramic、glass、metal.

使用条件/Operating conditions:

基材 Substrate	厚膜电路,氧化铝陶瓷, 陶瓷、玻璃、金属 thick film circuit, alumina ceramic, glass, metal
使用方法 Method of use	网孔印刷, Printing,
流平 Levelling	5-10min minutes at room temperature 室温下流平 5-10 分钟 (时间根据流平的实际情况决定)。
烘干 Curing conditions	通风烘箱烘烤 100-150℃, 10-15 分钟 (烘烤温度低于 300℃, 可根据烘烤的实际情况决定烘烤时间。) 100-150℃ 10-15 min
烧结 Firing Condition	隧道炉空气气氛下烧结, 峰值 550℃ (推荐值), 10~30 分钟。 (可根据实际需要, 烧结范围可在 430-600℃内调节,但峰值温度时间必须 10 分钟以上。) Atmospheric firing in belt furnace with peak time of 10~30 Minutes at 550℃ (According to actual needs, sintering range can be adjusted within 430-600℃)
稀释剂 Thinner	ST-1001

性能/Characteristics:

1. 浆料性能/Paste Characteristics:

性能 Characteristic	标准 Standard	测试方法及条件 Test method and conditions
1 细度 Fineness	≤8μm	FOG test
2 粘度 Viscosity	350~500Pa.s	Brookfield HBT utility cup and spindle (SC4-14/6R), 10rpm, 25±1℃, Brookfield HBT (博利飞) 粘度计, 转子 SC4-14/6R), 10rpm, 25±1℃
3 Appearance 外观	无色 Transparent	



2. 烧结后特性/Characteristics after curing:

在 1 烧结条件下, Check fired film produced under the conditions specified in 1),

特性 Characteristics	Standard 标准	测试方法和条件 Test method and conditions
4 外观 Appearance	紧凑致密 compact	目测&显微镜 Visual inspect & microscope

保存条件, 有效期/Storage condition and Term of validity

产品应在 5-15℃的环境温度下密封储存, 有效期为产品发货之日起 1 年。

The product shall be guaranteed for 1 year after shipping date, keep tightly under at 5-15℃

包装方式/Packaging method:

标准包装, 1000g/罐, 样品可提供 200 克小罐包装

Standard package 1000g/can, if you need sample to test, available 200g with small package.